

Advanced Packaging Market Size Projected US\$ 61.3 Billion with 7.2% of High CAGR by 2033: A Comprehensive Report by FMI

Prominent players in the United States are establishing fabrication facilities within the country to drive forward research and development initiatives.

NEWARK, DELAWARE, UNITED STATES OF AMERICA, November 28, 2023 /EINPresswire.com/ -- The global [advanced packaging market](#) is anticipated to be valued at US\$ 30.5 billion in 2023 and reach US\$ 61.3 billion by 2033. It will likely exhibit a considerable CAGR of 7.2% between 2023 and 2033.



Massive system-on-chip solutions would support a high density as packing technology advances. The semiconductor industry has created a new set of solutions known as advanced packaging due to an increasing focus on wafer-level packages and heterogeneous integrations.

In the past five years, there has been a significant increase in demand for advanced packaging technology, driven by the growing adoption of semiconductor integrated circuits in the automotive industry, as it aims to reduce costs, boost combined circuit throughput, and elevate overall performance.

Global sales of sophisticated packaging are on the rise, driven by the trend of electronics device miniaturization, as advanced semiconductor packaging swiftly outpaces conventional methods in markets worldwide.

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Micro-electromechanical systems (MEMS) are expected to be widely used, further driving demand for embedded die packaging solutions. The technology is not new, but owing to its high cost and low yield, it has been tailored for specific uses.

Key Takeaways from the Advanced Packaging Market Study

- In terms of end users, the consumer electronics segment is set to dominate by exhibiting around 7.0% CAGR from 2023 to 2033.

- The USA's advanced packaging industry is projected to create an absolute dollar opportunity of US\$ 4.7 billion through 2033.
- South Korea's advanced packaging market is expected to be worth US\$ 3.7 billion by 2033.
- China's advanced packaging market will likely be worth US\$ 15.5 billion by 2033.
- The United Kingdom's advanced packaging market is estimated to showcase a CAGR of 5.6% between 2023 and 2033.

“Electronic device performance has constantly been sought for various industrial, automotive, consumer, and mobile applications. Key companies are projected to develop all integrated circuit packaging, including fan-out wafer-level packages (FOWLP), with the help of special electronic solutions such as insulators and conductors,” - Says Ismail Sutaria, Principal consultant at Future Market Insights.

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Competitive Landscape:

Due to the demand for cutting-edge technology and quick-responding devices, renowned companies are set to dominate the global advanced packaging growth. These businesses continue to have a competitive advantage in the market owing to the elevated need for distinctive solutions for various applications.

Leading Key Players are:

Amkor Technology Inc.
 ASE Technology Holding Co. Ltd.
 China Wafer Level CSP Co. Ltd.
 ChipMOS Technologies Inc.
 FlipChip International LLC
 HANA Micron Inc.
 Jiangsu Changjiang Electronics Technology Co. Ltd.
 King Yuan Electronics Corp.
 Nepes Corporation
 Powertech Technology Inc.

Advanced Packaging Market Segmentation:

By Type:

Flip Chip Scale Package
Flip Chip Ball Grid Array
Wafer Level Chip Scale Packaging
5D/3D
Fan Out Wafer-level Packaging
Others

By End User:

Consumer Electronics
Healthcare
Industrial
Aerospace and Defense
Automotive
Other

By Region:

North America
Europe
Asia Pacific
Latin America
Middle East & Africa

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Get More Valuable Insights into Advanced Packaging Market:

In its new offering, Future Market Insights provides an unbiased analysis of the advanced packaging market, presenting historical demand data (2018 to 2022) and forecast statistics for 2023 to 2033.

The study incorporates compelling insights on the advanced packaging market based on type (flip chip scale package, flip chip ball grid array, wafer level chip scale package, 5D/3D, fan-out wafer-level packaging), end user (consumer electronics, automotive, industrial, healthcare, aerospace & defense), and region.

Authored By:

Ismail Sutaria (Lead Consultant, Packaging and Materials) has over 8 years of experience in market research and consulting in the packaging & materials industry. Ismail's strength lies in

identifying key challenges faced by the client and offering logical and actionable insights to equip the clients with strategic decision-making power.

Ismail has been an instrumental part of several transformational consulting assignments. His key skills include competitive benchmarking, opportunity assessment, macroeconomic analysis, and business transformation advisory. Ismail is an MBA holder in Marketing and has a Bachelor's Degree in Mathematics.

Ismail is a regular at industry conferences and expos and has been widely covered in electronic and print media. Ismail has been quoted in leading publications, including the European Pharmaceutical Review and the European Adhesive Tape Association.

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[Smart Packaging Market Size](#): The market is anticipated to achieve a valuation of US\$ 24.6 billion in 2023, with a projected increase to US\$ 38.3 billion by the year 2033. Over the decade from 2023 to 2033, the industry is poised for substantial growth, with a forecasted Compound Annual Growth Rate (CAGR) of 4.5%.

[Artificial Intelligence in Packaging Market Growth](#): The market size is anticipated to reach a valuation of US\$ 2,080.8 million in 2023, with a projected increase to US\$ 6,015.6 million by the year 2033. Sales in this market are poised to experience a noteworthy Compound Annual Growth Rate (CAGR) of 11.20% throughout the forecast period.

About Future Market Insights (FMI)

Future Market Insights, Inc. (ESOMAR certified, recipient of the Stevie Award, and a member of the Greater New York Chamber of Commerce) offers profound insights into the driving factors that are boosting demand in the market. FMI stands as the leading global provider of market intelligence, advisory services, consulting, and events for the Packaging, Food and Beverage, Consumer, Technology, Healthcare, Industrial, and Chemicals markets. With a vast team of over 5000 analysts worldwide, FMI provides global, regional, and local expertise on diverse domains and industry trends across more than 110 countries.

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